

Reply to Office Action of December 8, 2005

AMENDED CLAIM SET:

1. (currently amended) A method for producing an organic electroluminescent device by using a transfer material comprising at least one organic layer formed on a support, comprising the steps of superposing said transfer material on a first substrate having an electrode formed at least partially thereon such that said organic layer of said transfer material faces said electrode on said first substrate; applying heat and/or pressure thereto to form a laminate; and peeling said support from said laminate so that said organic layer is transferred onto said first substrate via said electrode, wherein said first substrate has a maximum surface roughness Rmax of 0 to 50 according to JIS B 0601-1982, assuming that the thickness of said organic layer is 100 obtained from a ratio of a maximum surface roughness Rmax (nm) of said first substrate to the thickness (nm) of said organic layer assuming that the thickness of said organic layer is 100, and wherein said organic layer has a glass transition temperature of from 40°C to the flow-starting temperature +40°C.

2. (original) The method of claim 1, wherein after the transfer of said organic layer onto said first substrate via said electrode, a second substrate having an electrode formed at least partially thereon is laminated to said organic layer on said first substrate.

3. (currently amended) The method of claim 2, wherein a surface of said second substrate, on which said electrode is formed, has a maximum surface roughness Rmax of 0 to 50 according to JIS B 0601-1982, assuming that the thickness of said organic layer is 100 obtained from a ratio of a maximum surface roughness Rmax (nm) of said second substrate to the thickness (nm) of said organic layer assuming that the thickness of said organic layer is 100.

4. (original) The method of claim 2, wherein at least one of said first and second substrates has a linear thermal expansion coefficient of 20 ppm/°C or less.

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5. (original) The method of claim 2, wherein a flat layer is formed on at least one of said first and second substrates.

6. (currently amended) The method of claim 5, wherein said flat layer is made of at least one material selected ~~form~~ from the group consisting of ultraviolet-curing organic compounds, electron beam-curing organic compounds, thermosetting organic compounds, inorganic oxides, and inorganic nitrides.

7. (currently amended) A method for producing an organic electroluminescent device by using a transfer material comprising at least one organic layer formed on a support formed on a plate having a pattern, comprising the steps of superposing said transfer material on a first substrate having an electrode formed at least partially thereon such that said organic layer of said transfer material faces said electrode on said first substrate; applying heat and/or pressure thereto to form a laminate; and peeling said ~~plate form~~ support from said laminate so that said organic layer is transferred onto said first substrate via said electrode, wherein said first substrate has a maximum surface roughness Rmax of 0 to 50 according to ~~JIS-B-0601-1982~~, assuming that the thickness of said organic layer is 100 obtained from a ratio of a maximum surface roughness Rmax (nm) of said first substrate to the thickness (nm) of said organic layer assuming that the thickness of said organic layer is 100, and wherein said organic layer has a glass transition temperature of from 40°C to the flow-starting temperature +40°C.

8. (original) The method of claim 7, wherein after the transfer of said organic layer onto said first substrate via said electrode, a second substrate having an electrode formed at least partially thereon is laminated to said organic layer on said first substrate.

9. (currently amended) The method of claim 8, wherein a surface of said second substrate, on which said electrode is formed, has a maximum surface roughness Rmax of 0 to 50 according to ~~JIS-B-0601-1982~~, assuming that the thickness of said organic layer is 100 obtained

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from a ratio of a maximum surface roughness Rmax (nm) of said second substrate to the thickness (nm) of said organic layer assuming that the thickness of said organic layer is 100.

10. (original) The method of claim 8, wherein at least one of said first and second substrates has a linear thermal expansion coefficient of 20 ppm/ $^{\circ}$ C or less.

11. (original) The method of claim 8, wherein a flat layer is formed on at least one of said first and second substrates

12. (currently amended) The method of claim 11, wherein said flat layer is made of at least one material selected ~~form~~ from the group consisting of ultraviolet-curing organic compounds, electron beam-curing organic compounds, thermosetting organic compounds, inorganic oxides, and inorganic nitrides.

13. (currently amended) An organic electroluminescent device produced by a method comprising the steps of superposing a transfer material comprising at least one organic layer formed on a support ~~icy~~ formed on a first substrate having an electrode formed at least partially thereon such that said organic layer of said transfer material faces said electrode on said first substrate; applying heat and/or pressure thereto to form a laminate; and peeling said support from said laminate so that said organic layer is transferred onto said first substrate via said electrode, wherein said first substrate has a maximum surface roughness Rmax of 0 to 50 ~~according to JIS B-0601-1982, assuming that the thickness of said organic layer is 100 obtained from a ratio of a maximum surface roughness Rmax (nm) of said first substrate to the thickness (nm) of said organic layer assuming that the thickness of said organic layer is 100, and wherein said organic layer has a glass transition temperature of from 40 $^{\circ}$ C to the flow-starting temperature +40 $^{\circ}$ C.~~

14. (original) The device of claim 13, wherein after the transfer of said organic layer onto said first substrate via said electrode, a second substrate having an electrode formed at least partially thereon is laminated to said organic layer on said first substrate.

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15. (currently amended) The device of claim 14, wherein a surface of said second substrate, on which said electrode is formed, has a maximum surface roughness R_{max} of 0 to 50 ~~according to JIS B 0601 1982, assuming that the thickness of said organic layer is 100 obtained from a ratio of a maximum surface roughness R_{max} (nm) of said second substrate to the thickness (nm) of said organic layer assuming that the thickness of said organic layer is 100.~~

16. (original) The device of claim 14, wherein at least one of said first and second substrates has a linear thermal expansion coefficient of 20 ppm/ $^{\circ}$ C or less.

17. (original) The device of claim 14, wherein a flat layer is formed on at least one of said first and second substrates.

18. (currently amended) The device of claim 17, wherein said flat layer is made of at least one material selected ~~form~~ from the group consisting of ultraviolet-curing organic compounds, electron beam-curing organic compounds, thermosetting organic compounds, inorganic oxides, and inorganic nitrides.

19. (currently amended) An organic electroluminescent device produced by a method comprising the steps of superposing a transfer material comprising at least one organic layer formed on a support formed on a plate having a pattern on a first substrate having an electrode formed at least partially thereon such that said organic layer of said transfer material faces said electrode on said first substrate; applying heat and/or pressure thereto to form a laminate; and peeling said ~~plate form support from~~ said laminate so that said organic layer is transferred onto said first substrate via said electrode, wherein said first substrate has a maximum surface roughness R_{max} of 0 to 50 ~~according to JIS B 0601 1982, assuming that the thickness of said organic layer is 100 obtained from a ratio of a maximum surface roughness R_{max} (nm) of said first substrate to the thickness (nm) of said organic layer assuming that the thickness of said~~

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organic layer is 100, and wherein said organic layer has a glass transition temperature of from 40°C to the flow-starting temperature +40°C.

20. (original) The device of claim 19, wherein after the transfer of said organic layer onto said first substrate via said electrode, a second substrate having an electrode formed at least partially thereon is laminated to said organic layer on said first substrate.

21. (currently amended) The device of claim 20, wherein a surface of said second substrate, on which said electrode is formed, has a maximum surface roughness Rmax of 0 to 50 ~~according to JIS B 0601-1982, assuming that the thickness of said organic layer is 100 obtained from a ratio of a maximum surface roughness Rmax (nm) of said second substrate to the thickness (nm) of said organic layer assuming that the thickness of said organic layer is 100.~~

22. (original) The device of claim 20, wherein at least one of said first and second substrates has a linear thermal expansion coefficient of 20 ppm/ $^{\circ}$ C or less.

23. (original) The device of claim 20, wherein a flat layer is formed on at least one of said first and second substrates.

24. (currently amended) The device of claim 23, wherein said flat layer is made of at least one material selected ~~from~~ from the group consisting of ultraviolet-curing organic compounds, electron beam-curing organic compounds, thermosetting organic compounds, inorganic oxides, and inorganic nitrides.